



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-31
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST7FMC2R7T6	U01R*840XXX3	A	959	2014-07-31
	Amount	UoM	Unit type	ST ECOPACK Grade
	645.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	64	L bend	
Comment	LQFP 64 14x14x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	U01R*840XXX3					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	17.303	mg	supplier	die	Silicon (Si)	7440-21-3		17.227	mg	995608	26709
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	751	20
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.015	mg	867	23
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.048	mg	2774	74
Lead-frame	Other inorganic materials	165.354	mg	supplier	alloy	Copper (Cu)	7440-50-8		158.140	mg	956376	245179
Lead-frame				supplier	alloy	Nickel (Ni)	7440-02-0		4.932	mg	29825	7646
Lead-frame				supplier	alloy	Silicium (Si)	7440-21-3		1.069	mg	6462	1657
Lead-frame				supplier	alloy	Magnesium (Mg)	7439-95-4		0.247	mg	1491	382
Lead-frame				supplier	coating	Nickel (Ni)	7440-02-0		0.886	mg	5360	1374
Lead-frame				supplier	coating	Palladium (Pd)	7440-05-3		0.057	mg	343	88
Lead-frame				supplier	coating	Gold (Au)	7440-57-5		0.024	mg	143	37
Die Attach	Other inorganic materials	3.617	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.848	mg	787500	4416
Die Attach				supplier	glue or soft solder	Urethane acrylate oligomer	na		0.253	mg	70000	392
Die Attach				supplier	glue or soft solder	Méthacrylate	na		0.253	mg	70000	392
Die Attach				supplier	glue or soft solder	Acrylate	na		0.253	mg	70000	392
Die Attach				supplier	glue or soft solder	NMP	872-50-4		0.009	mg	2500	14
Wires	Other inorganic materials	2.157	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		2.157	mg	1000000	3343
Encapsulation	Other inorganic materials	456.560	mg	supplier	Moulding Compound	Solid Epoxy Resin	na		31.963	mg	70009	49555
Encapsulation				supplier	Moulding Compound	Phenol Resin	na		22.831	mg	50006	35397
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		394.917	mg	864983	612274
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		2.283	mg	5001	3540
Encapsulation				supplier	Moulding Compound	Bismuth	7440-69-9		4.566	mg	10001	7079
Finishing	Other inorganic materials	0.010	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.009	mg	916800	14
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.001	mg	58700	1
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0